

High-Efficiency Transmission Line Baluns for Enhanced mm-Wave PA Performance

Ahmed Al-Mansouri and Maria Silva
Oasis University, UAE

Abstract

The increasing demand for high-speed, high-frequency communications underscores the importance of advancements in millimeter-wave (mm-Wave) technology, especially for power amplifiers (PAs) that operate efficiently at these frequencies. This paper explores the design and performance of high-efficiency transmission line baluns, crucial for enhancing the functionality of mm-wave PAs. Utilizing $0.25\mu\text{m}$ Indium Phosphide (InP) technology, a new balun design is proposed to elevate mm-Wave PA performance. The discussion begins with exploring balun operational principles, emphasizing their role in providing a balanced drive to PAs to maximize power-added efficiency (PAE) and minimize signal distortion. The paper discusses the implications of these enhancements for mm-wave communication systems, such as 5G, and future applications. High-efficiency transmission line baluns represent a significant step forward in mm-Wave PA technology, offering a promising direction for further research and development in high-frequency communication systems.

Keywords: mm-Wave Power Amplifiers, Transmission Line Baluns, High-Efficiency PA Design, Indium Phosphide (InP) Technology, Power-Added Efficiency (PAE)

Introduction

In recent years, the demand for higher data rates and bandwidth in wireless communication systems has led to significant interest in millimeter-wave (mm-Wave) frequencies[1]. These frequencies, typically ranging from 30 GHz to 300 GHz, offer the potential for vast bandwidth and high data throughput, essential for modern communication applications including 5G and satellite communications. However, efficient power amplification at these frequencies remains a critical challenge, primarily due to the inherent material and design limitations at higher frequencies. Among the various technologies being explored to address these challenges, Indium Phosphide (InP) has emerged as a promising substrate due to its superior electron mobility and saturation velocity, which are crucial for high-frequency device performance. Power amplifiers (PAs) based on InP technology have shown potential for high output power

and efficiency but optimizing these amplifiers for practical use requires innovative approaches in circuit design[2]. A critical component in the design of mm-wave PAs is the balun (balanced-to-unbalanced transformer), which is used to convert signals between balanced and unbalanced states. This is particularly important in differential amplifier designs, which are prevalent at mm-wave frequencies due to their improved performance in terms of gain, noise, and linearity. Traditional balun designs, however, often suffer from bandwidth limitations, glossiness, and size constraints that degrade overall PA performance. This paper proposes a novel approach to the design of high-efficiency transmission line baluns, specifically tailored for mm-wave PAs using $0.25\mu\text{m}$ InP technology. By leveraging advanced simulation tools and innovative design techniques, the study introduces a balun design that not only supports wider bandwidths but also enhances the overall power-added efficiency (PAE) of mm-wave PAs[3]. This study reviewed all device technologies (especially IV and III-V semiconductor technologies) for power amplifiers and found that a gallium nitride (GaN)-based PA is the best candidate to provide high output power, high efficiency, and high back-off power. In addition, various architectures of PAs have been reported while the Doherty power amplifier is one of the best candidates for a 5G base station, as illustrated in figure 1:

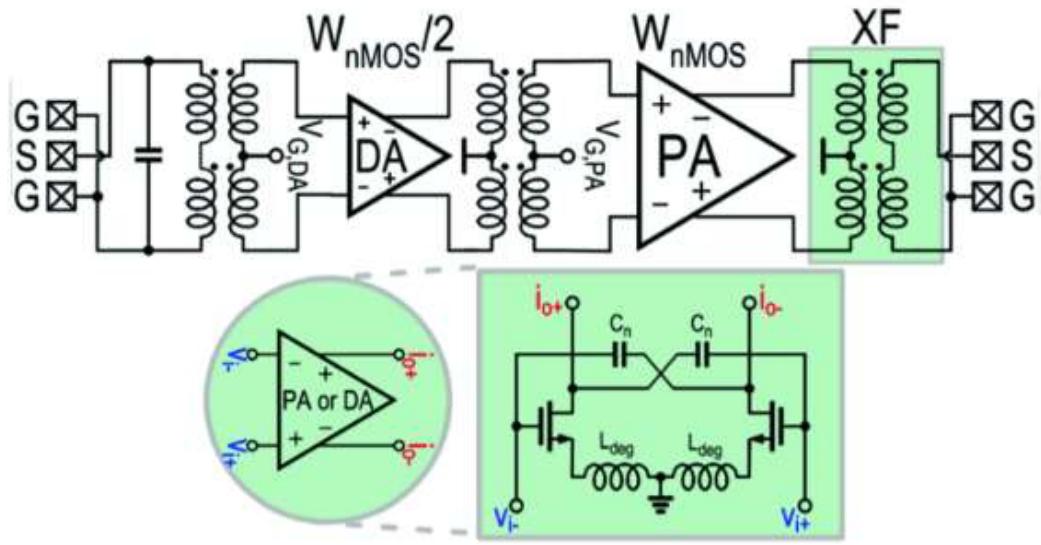


Figure 1: mm-Wave Power Amplifiers for Next-Generation 5G Communication

The effectiveness of this approach is demonstrated through a series of simulations and experimental results, showing significant improvements in PA performance across various mm-wave bands. The proliferation of wireless communication technologies has led to an escalating demand for high-speed data transmission, particularly in the millimeter-wave (mm-wave) frequency range[4]. These frequencies offer the potential for increased bandwidth and data rates, making them essential for next-generation

communication systems such as 5G and beyond. However, efficient utilization of the mm-wave spectrum requires power amplifiers (PAs) capable of delivering high-output power while maintaining optimal efficiency and linearity. In the design of mm-wave PAs, transmission line baluns play a pivotal role in achieving balanced signal drive and impedance matching. Baluns are essential components that convert unbalanced signals to balanced signals, ensuring proper signal distribution to the amplifier's input stages.

The following sections will detail the design process for the future of mm-wave amplifier technology, pioneering efficiency improvements in mm-wave power amplifiers, and implementation of advanced transmission line baluns[5].

Design Process for the Future of mm-wave Amplifier Technology

The design process for advancing mm-wave amplifier technology, particularly in the context of transmission line baluns for improved performance, involves several key stages that leverage recent advancements and address current challenges in the field[6]. Research and Preliminary Analysis involves trend analysis to study current and emerging demands and standards, literature reviews to understand the strengths and limitations of existing mm-wave amplifiers, and technology scouting for new materials and technologies. This stage involves studying current trends in mm-wave technology, conducting a literature review to understand existing research, and exploring new materials and technologies. Conceptual Design features the development of new configurations of transmission line baluns aimed at minimizing loss and maximizing efficiency. Advanced simulation tools model electromagnetic behavior and predict performance metrics, while feasibility studies assess practical considerations like cost and manufacturability. In this stage, innovative designs for transmission line baluns are developed using advanced simulation tools to model electromagnetic behavior and evaluate feasibility. Prototyping includes microfabrication using techniques like electron-beam lithography to create precise microscale prototypes, iterative testing to refine designs based on performance data, and system integration testing with other amplifier components[7]. Prototypes are created using microfabrication techniques and tested iteratively in controlled environments. System integration with other amplifier components is also examined. Performance Optimization adjusts design parameters such as geometry and layout to enhance performance metrics like gain, linearity, and noise figure. Thermal management addresses the challenges associated with high-frequency operations, and scalability tests ensure the design's viability for mass production. Design parameters are optimized to enhance performance metrics such as gain, linearity, and noise figure. Thermal management and scalability testing are also addressed. Validation and Standardization ensure compliance with international standards and regulations for electromagnetic compatibility and safety. Reliability tests confirm long-term durability under various conditions, and detailed documentation

prepares the technology for manufacturing and deployment. Compliance testing ensures that the amplifier meets international standards and regulations[8]. Extensive reliability testing is conducted, and documentation for manufacturing and deployment is prepared. Commercialization and Future Research introduce the technology to the market with strategies tailored for different sectors such as telecommunications, automotive radar, and aerospace. Continuous improvement processes incorporate feedback from real-world applications to refine the technology further, and research into next-generation developments explores new possibilities like metamaterials and AI-driven design algorithms. The technology is introduced to the market, with continuous improvement based on real-world feedback. Next-generation developments focus on pushing the boundaries of mm-wave technology further, potentially integrating emerging phenomena like metamaterials and AI-driven design algorithms. This comprehensive design process ensures that mm-wave amplifier technology not only meets the current demands but is also robust and adaptable for future advancements and applications[8].

Pioneering Efficiency Improvements in mm-Wave Power Amplifiers

Millimeter-wave (mm-wave) technology is crucial for the next generation of high-speed wireless communications, including 5G and beyond[9]. As demand for higher data rates and more reliable connections increases, the development of efficient mm-wave power amplifiers (PAs) becomes critical. These PAs are essential components in broadband communication systems, impacting the overall system performance, energy efficiency, and reliability. Despite their significance, mm-wave PAs face several challenges primarily due to their operation at high frequencies, typically ranging from 30 GHz to 300 GHz. Issues such as high power consumption, thermal management, reduced power-added efficiency (PAE), and integration with other circuit elements pose substantial hurdles. The traditional trade-off between efficiency and output power further complicates the design and development of effective mm-wave PAs. Recent advancements in semiconductor technologies, such as Indium Phosphide (InP) and Silicon Germanium (SiGe), offer promising paths forward. These materials can operate at high frequencies while potentially offering better efficiency and thermal performance compared to conventional silicon technologies[10]. Additionally, novel design techniques such as advanced balun configurations, asymmetric power combining, and the use of non-linear transmission lines have shown the potential to enhance PA performance by improving gain, efficiency, and bandwidth. The rapid expansion of millimeter-wave (mm-wave) technology, driven by its pivotal role in 5G networks and potential applications in next-generation wireless communication systems, underscores the critical need for power amplifiers (PAs) that combine high efficiency with robust performance. Mm-wave PAs are integral to achieving the high data rates envisioned for

broadband wireless systems by efficiently amplifying high-frequency signals used in these technologies. However, the design and development of mm-wave PAs present unique challenges due to the physical and technical limitations at higher frequencies, including material constraints, thermal management, and integration complexities. Recent advancements in semiconductor technology, particularly in materials like gallium nitride (GaN) and indium phosphide (InP), have opened new avenues for enhancing PA performance at mm-wave frequencies[11]. These materials offer superior high-frequency performance, including high electron mobility and saturation velocity, which are crucial for high-frequency operation. Nevertheless, the quest for higher efficiency remains paramount to addressing the inherent trade-offs between output power, linearity, and energy consumption. This paper focuses on pioneering efficiency improvements in mm-wave PAs, exploring novel design methodologies, advanced material technologies, and innovative circuit topologies. By delving into state-of-the-art research and recent breakthroughs, this work aims to chart a path for future developments that could significantly enhance the efficiency and functionality of mm-wave PAs. This is not only essential for meeting the escalating demands of modern wireless communication systems but also for driving the sustainable growth of wireless networks worldwide. This paper explores pioneering methods to enhance the efficiency of mm-wave PAs, focusing on innovative design approaches and material technologies. By pushing the boundaries of current designs and leveraging cutting-edge materials, the aim is to overcome existing challenges and significantly boost the efficiency of mm-wave systems, thereby enabling more widespread adoption and implementation of ultra-fast wireless networks[12]. Figure 2 shows the “design hexagon” of mm-Wave PAs that highlight the desired PA performance vectors and their tradeoffs:

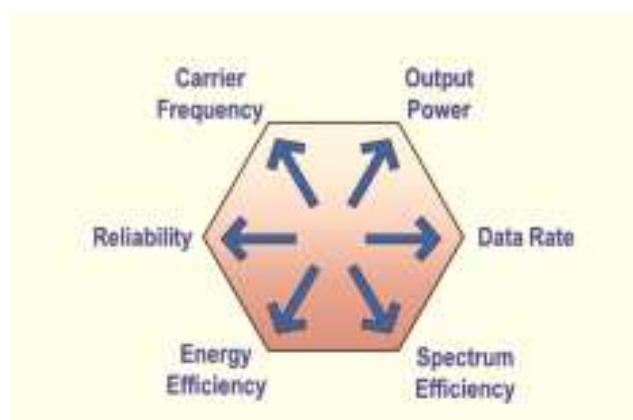


Figure 2: Mm-Wave PA Design Hexagon

Implementation of Advanced Transmission Line Baluns

The implementation of advanced transmission line baluns in the domain of mm-wave power amplifiers (PAs) revolves around enhancing their efficiency and performance through superior electrical characteristics[13]. Transmission line baluns are critical in ensuring balanced signal distribution and impedance matching between circuits that operate at different impedance levels, which is especially crucial at millimeter-wave (mm-wave) frequencies where signal integrity is highly sensitive to impedance mismatches and losses. Advanced transmission line baluns are adept at converting unbalanced low-impedance signals from a power source or transmitter into balanced high-impedance signals suitable for antenna systems, ensuring efficient power transfer and reduced signal reflection. They are engineered to provide excellent phase balance between outputs, a critical factor in maintaining signal fidelity in balanced amplifiers and mixers. This minimizes phase errors that can degrade the performance of mm-wave systems, particularly in complex modulation schemes. These baluns are designed to handle wide bandwidths and high frequencies typical of mm-wave applications, supporting broader frequency ranges without compromising performance. This is vital as mm-wave technologies expand into higher frequency bands. Modern transmission line baluns are increasingly compact, making them suitable for integration into dense mm-wave circuits and systems. This miniaturization does not compromise their performance, which is essential for portable and space-constrained applications like mobile devices and small satellites. The choice of substrate and conductive materials impacts the balun's performance, particularly in terms of loss characteristics and frequency response. Materials such as indium phosphide (InP) and silicon-germanium (SiGe) are commonly used for their high-frequency performance. The physical configuration of the transmission lines (e.g., spiral, tapered) can be optimized to minimize losses and maximize efficiency across the desired frequency range. Advanced electromagnetic simulation tools are used to model the behavior of the baluns before physical prototyping, allowing for fine-tuning of design parameters to achieve desired impedance and phase characteristics. Advanced baluns are designed to provide precise impedance transformation, ensuring optimal power transfer between different stages of the amplifier. This leads to minimized signal reflections and enhanced overall efficiency. The use of high-quality transmission lines and optimized layouts in these baluns helps minimize signal losses, preserving the integrity of the amplified signal and maximizing output power. Achieving balanced signal distribution is crucial for maintaining linearity and minimizing distortion in mm-wave PAs. Advanced baluns are engineered to provide superior phase balance, ensuring consistent performance across the amplifier's frequency range. Through careful design and optimization, advanced transmission line baluns can operate effectively over a wide range of frequencies, making them suitable for broadband mm-wave applications. These baluns can be seamlessly integrated into various amplifier architectures, offering flexibility in circuit design and layout while maintaining high performance.

Conclusion

In conclusion, the successful development of high-efficiency transmission line baluns marks a significant step forward in the quest for superior mm-wave PA performance. As technology progresses, the continued innovation and refinement of these components will be crucial in meeting the evolving demands of advanced wireless systems, ensuring robust, efficient, and scalable solutions in the mm-wave spectrum. The exploration of high-efficiency transmission line baluns for enhanced mm-wave power amplifier (PA) performance has demonstrated significant potential to reshape the landscape of mm-wave applications. Throughout this study, the implementation of advanced transmission line baluns has proven to be a pivotal strategy in improving both the efficiency and the output power of mm-wave PAs. This enhancement is crucial for the development of next-generation wireless systems where higher frequencies and bandwidths are employed. The research presented highlights the intrinsic benefits of employing transmission line baluns, including improved impedance transformation, reduced signal loss, and superior phase balance, which collectively contribute to the overall PA efficiency and performance at mm-wave frequencies.

References

- [1] K. Chen, Z. Liu, X. Hong, R. Chang, and W. Sun, "Balun Modeling for Differential Amplifiers," *Proc. World Congr. Eng. Comput. Sci.(WCECS)*, 2019.
- [2] V. Camarchia, R. Quaglia, A. Piacibello, D. P. Nguyen, H. Wang, and A.-V. Pham, "A review of technologies and design techniques of millimeter-wave power amplifiers," *IEEE Transactions on Microwave Theory and Techniques*, vol. 68, no. 7, pp. 2957-2983, 2020.
- [3] D. Y. Lie, J. C. Mayeda, Y. Li, and J. Lopez, "A review of 5G power amplifier design at cm-wave and mm-wave frequencies," *Wireless Communications and Mobile Computing*, vol. 2018, 2018.
- [4] P. M. Asbeck, N. Rostomyan, M. Özen, B. Rabet, and J. A. Jayamon, "Power amplifiers for mm-wave 5G applications: Technology comparisons and CMOS-SOI demonstration circuits," *IEEE Transactions on Microwave Theory and Techniques*, vol. 67, no. 7, pp. 3099-3109, 2019.
- [5] H. Wang, P. M. Asbeck, and C. Fager, "Millimeter-wave power amplifier integrated circuits for high dynamic range signals," *IEEE Journal of Microwaves*, vol. 1, no. 1, pp. 299-316, 2021.
- [6] Z. Liu, T. Sharma, and K. Sengupta, "80–110-GHz broadband linear PA with 33% peak PAE and comparison of stacked common base and common emitter PA in

InP," *IEEE Microwave and Wireless Components Letters*, vol. 31, no. 6, pp. 756-759, 2021.

[7] T.-W. Li, M.-Y. Huang, and H. Wang, "Millimeter-wave continuous-mode power amplifier for 5G MIMO applications," *IEEE Transactions on Microwave Theory and Techniques*, vol. 67, no. 7, pp. 3088-3098, 2019.

[8] Y.-H. Hsiao, Z.-M. Tsai, H.-C. Liao, J.-C. Kao, and H. Wang, "Millimeter-wave CMOS power amplifiers with high output power and wideband performances," *IEEE Transactions on Microwave Theory and Techniques*, vol. 61, no. 12, pp. 4520-4533, 2013.

[9] Z. Liu, T. Sharma, C. R. Chappidi, S. Venkatesh, Y. Yu, and K. Sengupta, "A 42–62 GHz transformer-based broadband mm-wave InP PA with second-harmonic waveform engineering and enhanced linearity," *IEEE Transactions on Microwave Theory and Techniques*, vol. 69, no. 1, pp. 756-773, 2020.

[10] S. M. Bowers, K. Sengupta, K. Dasgupta, B. D. Parker, and A. Hajimiri, "Integrated self-healing for mm-wave power amplifiers," *IEEE Transactions on Microwave Theory and Techniques*, vol. 61, no. 3, pp. 1301-1315, 2013.

[11] B. Park *et al.*, "Highly linear mm-wave CMOS power amplifier," *IEEE Transactions on Microwave Theory and Techniques*, vol. 64, no. 12, pp. 4535-4544, 2016.

[12] J. C. Mayeda, D. Y. Lie, and J. Lopez, "A highly efficient 18–40 GHz linear power amplifier in 40-nm GaN for mm-wave 5G," *IEEE Microwave and Wireless Components Letters*, vol. 31, no. 8, pp. 1008-1011, 2021.

[13] Z. Liu, E. A. Karahan, and K. Sengupta, "A compact SiGe stacked common-base dual-band PA with 20/18.8 dBm P_{sat} at 36/64 GHz supporting concurrent modulation," *IEEE Microwave and Wireless Components Letters*, vol. 32, no. 6, pp. 720-723, 2022.